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Low k Dielectric Materials

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Message from the Guest Editor

Dear Colleagues,

For Low k dielectric materials, the value of dielectric constant is less than the dielectric constant of silicon dioxide. Such materials are of great importance for multi-level interconnections of nanoelectronics and radio frequency (RF) devices and circuits. Other applications include optoelectronics, 3-D integrated circuits, microelectromechanical systems (MEMS), nanoelectromechanical (NEMS), sensors and detectors and packaging of various types of devices and circuits. All topics related to synthesis, and properties of low-k dielectrics, various processing techniques, process integration, performance and reliability of low-K based devices, circuits and systems are of interest for this journal issue.

Dr. Rajendra Singh
Guest Editor



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